ABSTRACT

There is provided a film peeling device (100) for peeling a film (3) stuck onto a first portion (121) containing a peripheral portion of a wafer (20) and also stuck onto a second portion (122) located inward with respect to the first portion, comprising: a moving means (61, 62) for relatively moving the first portion and/or second portion so that the film of the first portion of the wafer can be located at a position higher than the film of the second portion; a tape drawing means (142) for drawing out a peeling tape (103) onto the film stuck onto the first and the second portion; and a peeling means (146) for peeling the film from the first and the second portion of the wafer when the peeling tape drawn out from the tape drawing means is pressed against only the first portion film and moved along the first portion. Due to the foregoing, it is possible to prevent the wafer from being damaged at the time of peeling the front surface protection film.